

SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCTION OF SAME

Abstract Of The Disclosure

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Thin semiconductor device, especially a thin package, which reduces and achieves uniform mounting height, not requiring mounting of individual chips, improves manufacturing yield, without being affected by variation in chip thickness, enables testing altogether, and process for producing same, the semiconductor mounted with back surface exposed upward, on top of an insulating substrate having throughholes in thickness direction, the area around semiconductor side surfaces being sealed by a resin layer, metal interconnections on the bottom surface of the substrate define bottom portions of throughholes of the substrate, a solder resist layer having throughholes in the thickness direction covers the bottom surface of metal interconnections and substrate, terminals extending downward from the active surface of the semiconductor are inserted into throughholes of the substrate, conductive filler fills gaps between the terminals and the throughholes of the substrate, and connection terminal and interconnections are electrically connected.
